

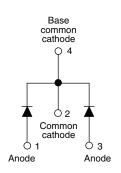
www.vishay.com

Vishay Semiconductors

HALOGEN FREE

Ultrafast Rectifier, 2 x 3 A FRED Pt®

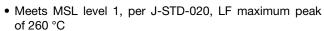




PRIMARY CHARACTERISTICS						
I _{F(AV)}	2 x 3 A					
V_{R}	200 V					
V _F at I _F	0.9 V					
t _{rr} typ.	See Recovery table					
T _J max.	175 °C					
Package	DPAK (TO-252AA)					
Circuit configuration	Common cathode					

FEATURES

- Ultrafast recovery time
- Low forward voltage drop
- · Low leakage current
- 175 °C operating junction temperature



 Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

DESCRIPTION / APPLICATIONS

VS-MURD620CT-M3 is the state of the art ultrafast recovery rectifier specifically designed with optimized performance of forward voltage drop and ultrafast recovery time.

The planar structure and the platinum doped life time control, guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in the output rectification stage of SMPS, UPS, DC/DC converters as well as freewheeling diode in low voltage inverters and chopper motor drives.

Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

ABSOLUTE MAXIMUM RATINGS							
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS			
Peak repetitive reverse voltage	V_{RRM}		200	V			
Average rectified forward current per device	I _{F(AV)}	Total device, rated V _R , T _C = 146 °C	6				
Non-repetitive peak surge current	I _{FSM}		50	Α			
Peak repetitive forward current per diode	I _{FM}	Rated V _R , square wave, 20 kHz, T _C = 146 °C	6				
Operating junction and storage temperatures	T _J , T _{Stg}		-65 to +175	°C			

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS	TYP.	MAX.	UNITS		
Breakdown voltage, blocking voltage	V _{BR} , V _R	Ι _R = 100 μΑ	200	-	-		
		I _F = 3 A	-	0.9	1.0	7	
	V	I _F = 3 A, T _J = 125 °C	A, T _J = 125 °C - 0.78		0.96	V	
Forward voltage	V _F	I _F = 6 A	-	1	1.2		
		I _F = 6 A, T _J = 125 °C	-	0.89	1.13		
Deverage leaders assument		$V_R = V_R$ rated	-	-	5		
Reverse leakage current	I _R	$T_J = 125$ °C, $V_R = V_R$ rated	-	-	250	μA	
Junction capacitance	C _T	V _R = 200 V	-	12	-	pF	
Series inductance	L _S	Measured lead to lead 5 mm from package body	-	8.0	-	nH	





DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)								
PARAMETER	SYMBOL	TEST CO	MIN.	TYP.	MAX.	UNITS		
		$I_F = 1.0 \text{ A}, dI_F/dt = 50 \text{ A}$	$I_F = 1.0 \text{ A}, dI_F/dt = 50 \text{ A/}\mu\text{s}, V_R = 30 \text{ V}$		-	35		
Povorno rocovena timo	t _{rr}	$I_F = 0.5 \text{ A}, I_R = 1.0 \text{ A}, I_{REC} = 0.25 \text{ A}$		-	-	25		
Reverse recovery time		T _J = 25 °C	$I_F = 3 A$ $dI_F/dt = 200 A/\mu s$ $V_R = 160 V$	-	19	-	ns	
		T _J = 125 °C		-	26	-		
Peak recovery current	I _{RRM}	T _J = 25 °C		-	3.1	-	А	
		T _J = 125 °C		-	4.6	-		
Reverse recovery charge	0	T _J = 25 °C		-	30	-	nC	
	Q _{rr}	T _J = 125 °C		-	60	-		

THERMAL - MECHANICAL SPECIFICATIONS							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Maximum junction and storage temperature range	T _J , T _{Stg}		-65	-	175	°C	
Thermal resistance, junction to case per leg	R _{thJC}		-	-	9.0		
Thermal resistance, junction to ambient per leg	R _{thJA}		-	-	80	°C/W	
Thermal resistance, case to heatsink	R _{thCS}	Mounting surface, flat, smooth, and greased	-	-	-		
Weight			-	0.3	-	g	
vveigni			-	0.01	-	oz.	
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)	
Marking device		Case style DPAK (TO-252AA)	MURD620CT			•	

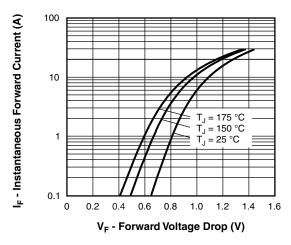


Fig. 1 - Typical Forward Voltage Drop Characteristics

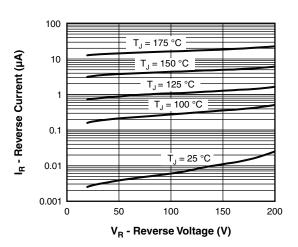


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

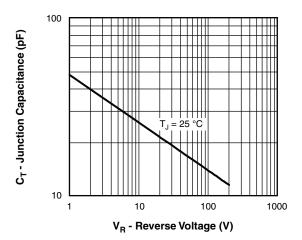


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

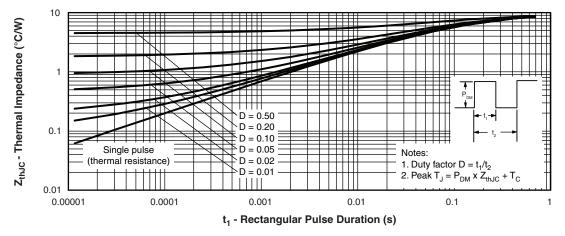


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics



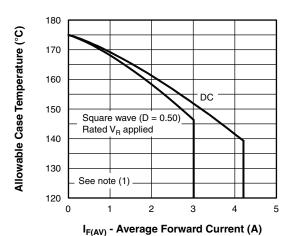


Fig. 5 - Maximum Allowable Case Temperature vs.
Average Forward Current

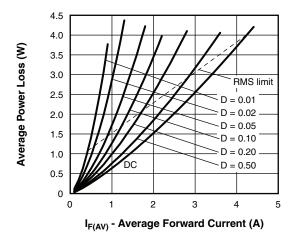


Fig. 6 - Forward Power Loss Characteristics

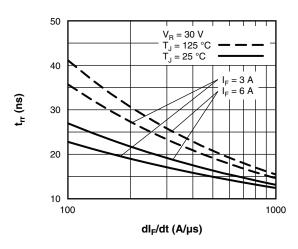


Fig. 7 - Typical Reverse Recovery Time vs. dI_F/dt

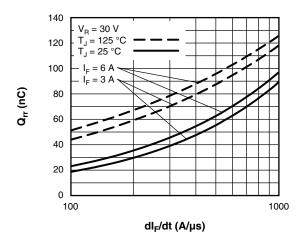


Fig. 8 - Typical Stored Charge vs. dI_F/dt

Note

 $\begin{array}{ll} \text{(1)} & \text{Formula used: } T_C = T_J - (Pd + Pd_{REV}) \times R_{thJC}; \\ Pd = \text{forward power loss} = I_{F(AV)} \times V_{FM} \text{ at } (I_{F(AV)}/D) \text{ (see fig. 6)}; \\ Pd_{REV} = \text{Inverse power loss} = V_{R1} \times I_R \text{ (1 - D); } I_R \text{ at } V_{R1} = \text{rated } V_R \\ \end{array}$



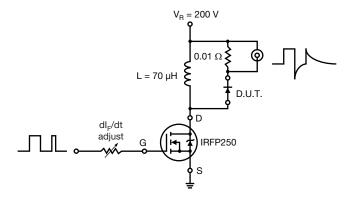
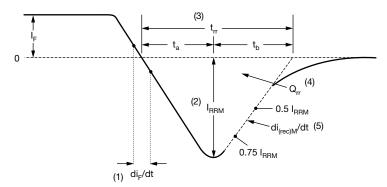


Fig. 9 - Reverse Recovery Parameter Test Circuit



- (1) di_F/dt rate of change of current through zero crossing
- (2) I_{RRM} peak reverse recovery current
- (3) $\rm t_{rr}$ reverse recovery time measured from zero crossing point of negative going $\rm l_{r}$ to point where a line passing through 0.75 $\rm l_{RRM}$ and 0.50 $\rm l_{RRM}$ extrapolated to zero current.
- (4) $\mathbf{Q}_{\rm rr}$ area under curve defined by $\mathbf{t}_{\rm rr}$ and $\mathbf{I}_{\rm RRM}$

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

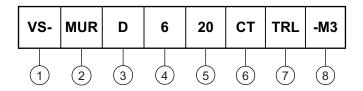
(5) di_{(rec)M}/dt - peak rate of change of current during t_b portion of t_{rr}

Fig. 10 - Reverse Recovery Waveform and Definitions



ORDERING INFORMATION TABLE

Device code



1 - Vishay Semiconductors product

2 - Ultrafast MUR series

3 - D = D-PAK

4 - Current rating (6 = 6 A)

Voltage rating (20 = 200 V)

- CT = center tap (dual) TR = tape and reel

TRL = tape and reel (left oriented)
TRR = tape and reel (right oriented)

8 - Environmental digit:

-M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

ORDERING INFORMATION (Example)							
PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION				
VS-MURD620CT-M3	75	3000	Antistatic plastic tube				
VS-MURD620CTTR-M3	2000	2000	13" diameter reel				
VS-MURD620CTTRL-M3	3000	3000	13" diameter reel				
VS-MURD620CTTRR-M3	3000	3000	13" diameter reel				

LINKS TO RELATED DOCUMENTS					
Dimensions <u>www.vishay.com/doc?95627</u>					
Part marking information	www.vishay.com/doc?95176				
Packaging information	www.vishay.com/doc?95033				



D-PAK (TO-252AA) "M"

DIMENSIONS in millimeters and inches



SYMBOL	MILLIN	IETERS	INC	NOTES	
STIVIBUL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	2.18	2.39	0.086	0.094	
A1	-	0.13	-	0.005	
b	0.64	0.89	0.025	0.035	
b2	0.76	1.14	0.030	0.045	
b3	4.95	5.46	0.195	0.215	3
С	0.46	0.61	0.018	0.024	
c2	0.46	0.89	0.018	0.035	
D	5.97	6.22	0.235	0.245	5
D1	5.21	-	0.205	1	3
Е	6.35	6.73	0.250	0.265	5
E1	4.32	-	0.170	-	3

SYMBOL	MILLIN	IETERS	INC	HES	NOTES
STINIBOL	MIN.	MAX.	MIN.	MAX.	NOTES
е	2.29 BSC		0.090	BSC	
Н	9.40	10.41	0.370	0.410	
L	1.40	1.78	0.055	0.070	
L1	2.74 BSC		0.108 REF.		
L2	0.51	BSC	0.020 BSC		
L3	0.89	1.27	0.035	0.050	3
L4	-	1.02	-	0.040	
L5	1.14	1.52	0.045	0.060	2
Ø	0°	10°	0°	10°	
Ø1	0°	15°	0°	15°	
Ø2	25°	35°	25°	35°	

Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Lead dimension uncontrolled in L5
- (3) Dimension D1, E1, L3 and b3 establish a minimum mounting surface for thermal pad
- (4) Section C C dimension apply to the flat section of the lead between 0.13 and 0.25 mm (0.005 and 0.10") from the lead tip
- (5) Dimension D, and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (6) Dimension b1 and c1 applied to base metal only
- (7) Datum A and B to be determined at datum plane H
- (8) Outline conforms to JEDEC® outline TO-252AA



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